



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP ap5000 All-in-One Point of Sale System

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3 (system board; HDD board; PCI board)
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	1
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	system fan, psu fan, heatsink fan	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Screw Driver	0
Philips #2 Screw Driver	1
Dikes Pliers (picture 15)	1
Description #4	
Description #5	

3.0 Product Disassembly Process

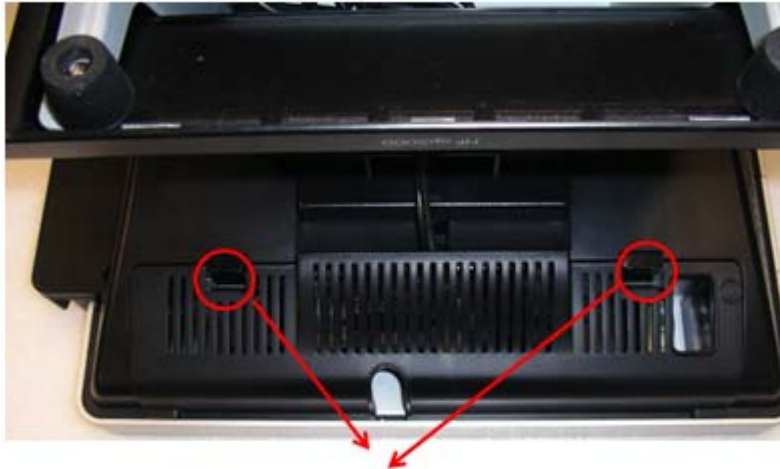
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Step1~5 : Remove VFD module.
2. Step 6~7 : Remove Counter Base Assembly
3. Step 8~10 : Remove MSR assembly.
4. Step 11 : HDD Door and Side IO Cover.
5. Step 12~13 : Remove Back Cover Assembly.
6. Step 14~20 : Remove MB Assembly.
7. Step 21~23 : Remove PCI board.
8. Step 24~27 : Remove Inverter board.
9. Step 28~34 : Take apart LCD Assembly.
10. Step 35~36 : Take apart MSR Assembly.
11. Step 37~42 : Take apart VFD Assembly.
12. Step 43~51 : Take apart Base Assembly.
13. Step 52~56 : Take apart MB Assembly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

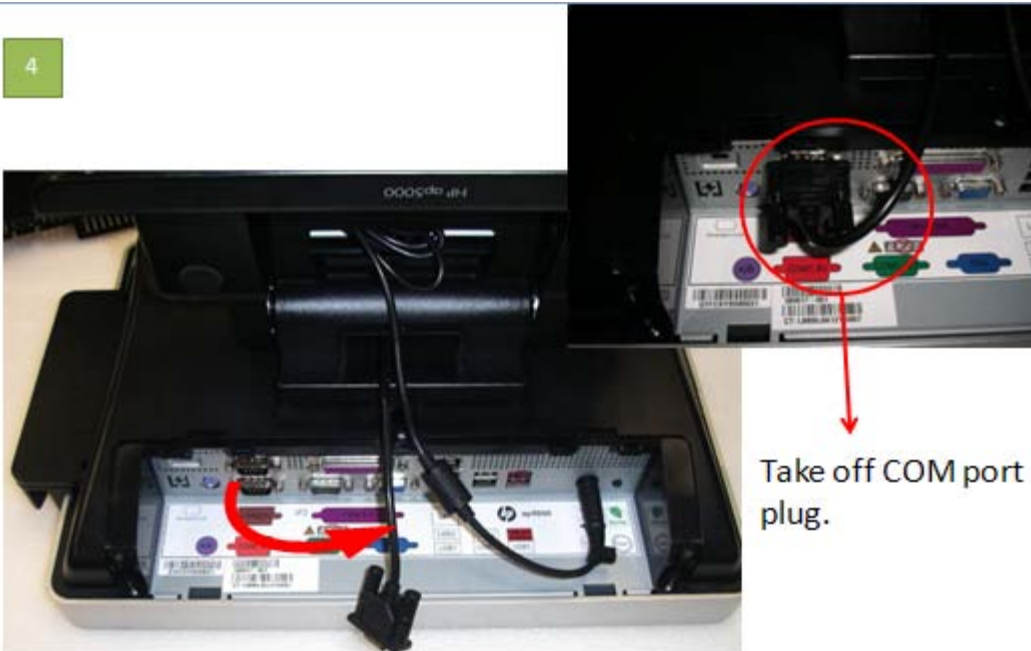


3



Click these two tabs to open IO cover.

4



Take off COM port plug.

5 Pull the VFD assembly upward to take off it.



6
1 Release one screw from base cover back.



2. Take off Power Jack



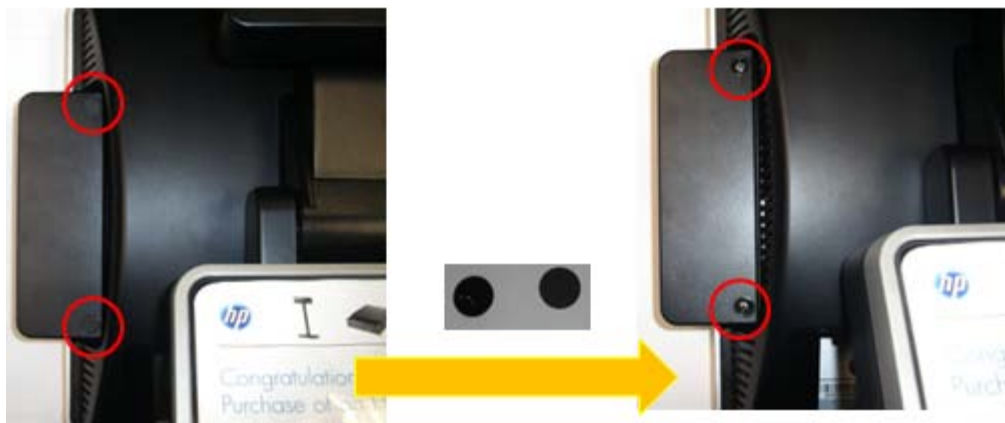
3 Release another screw from base cover bottom.



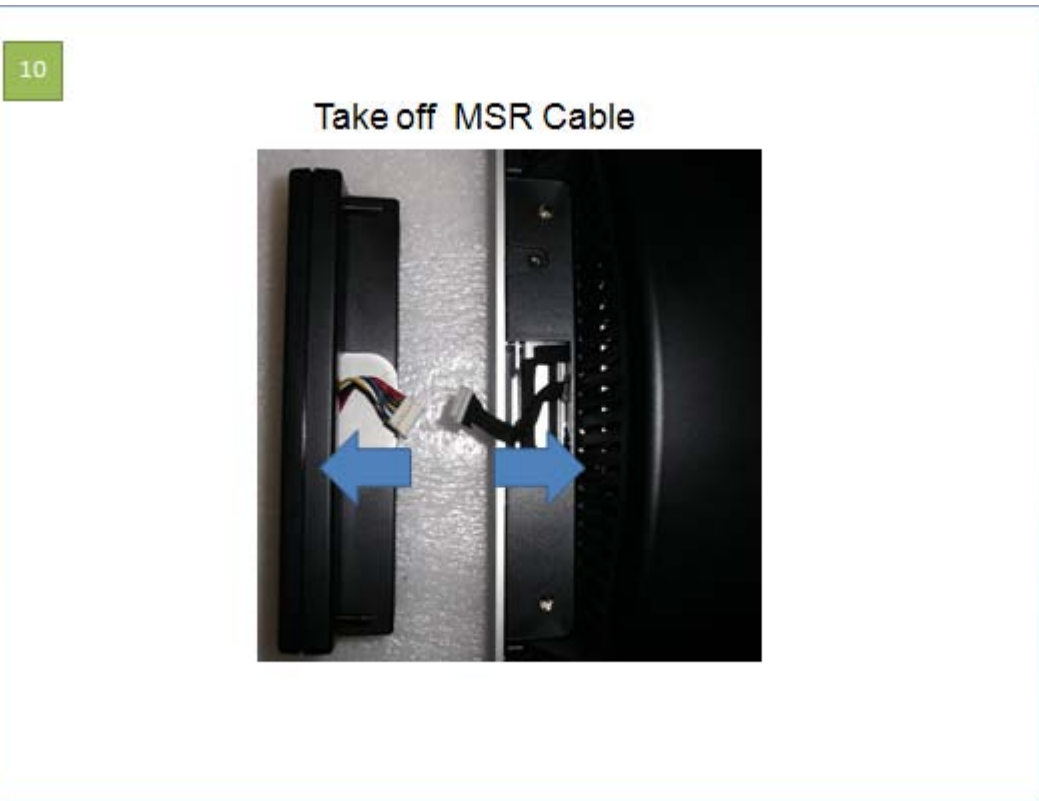
7 Pull the base unit downward to remove it.



8



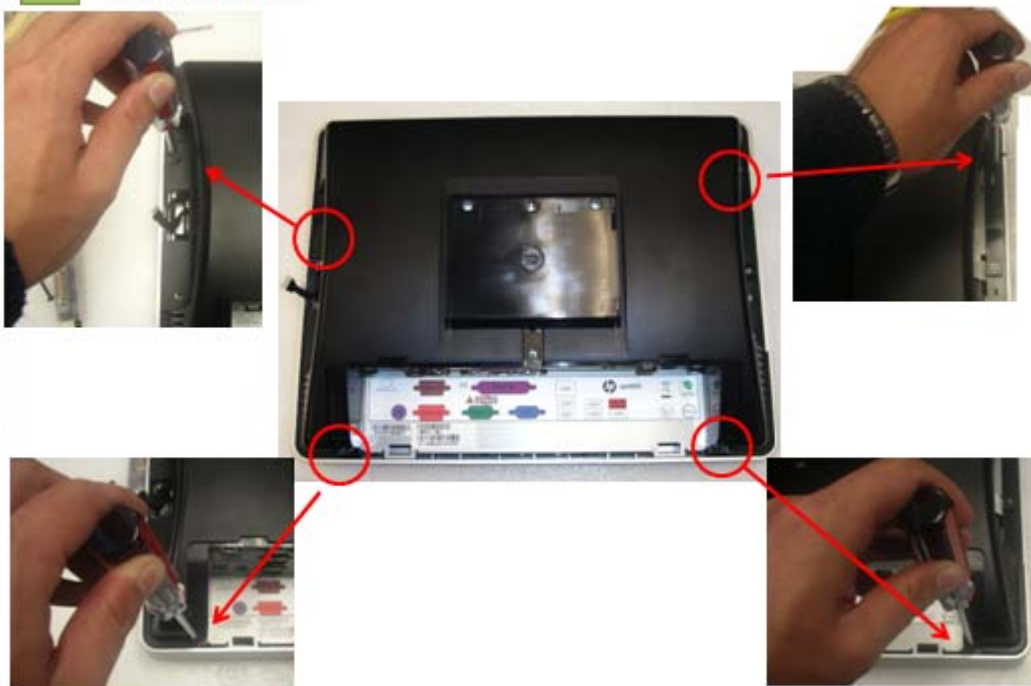
Remove Circular Mylar from screw hole.



- 11 Release HDD Door screw to take off HDD Door and Side IO Cover.

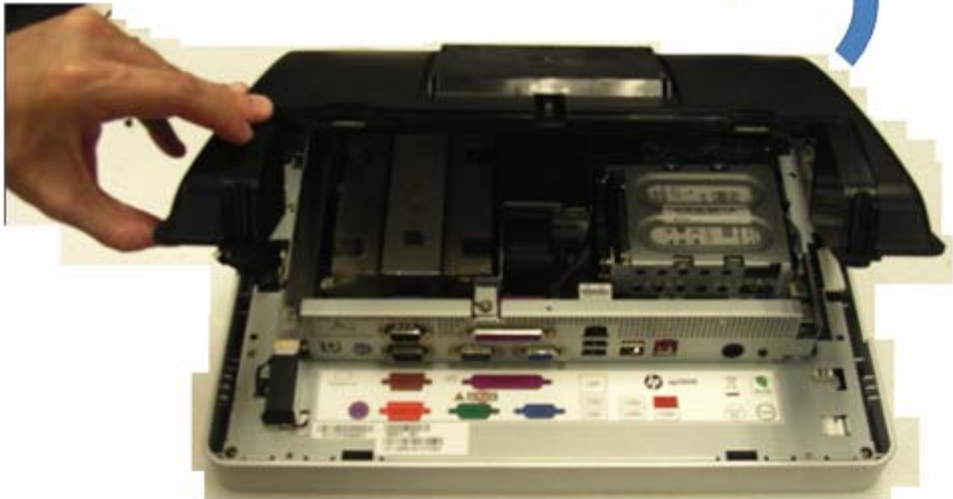


- 12 Release 4 pcs screw which is used to fix Back cover with Front Cover.



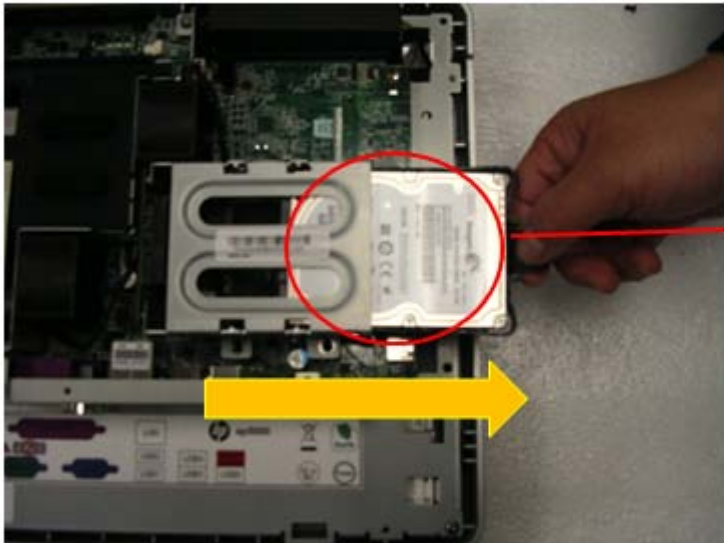
13

Take off Back Cover



14

Take off HDD and HDD carrier.

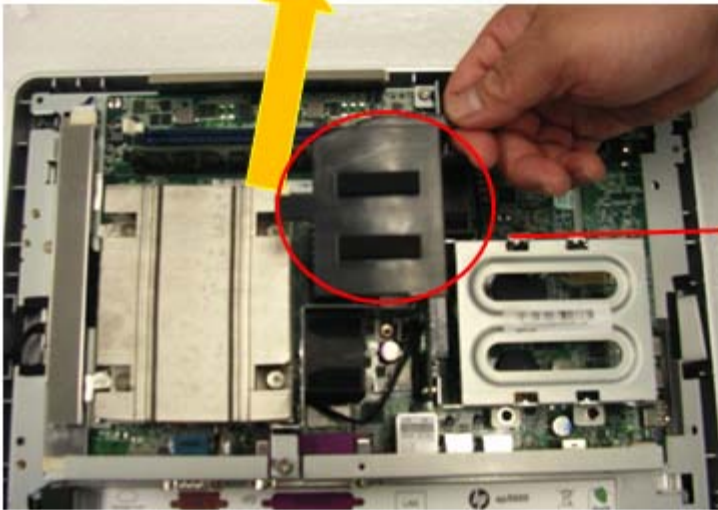


HDD and HDD carrier



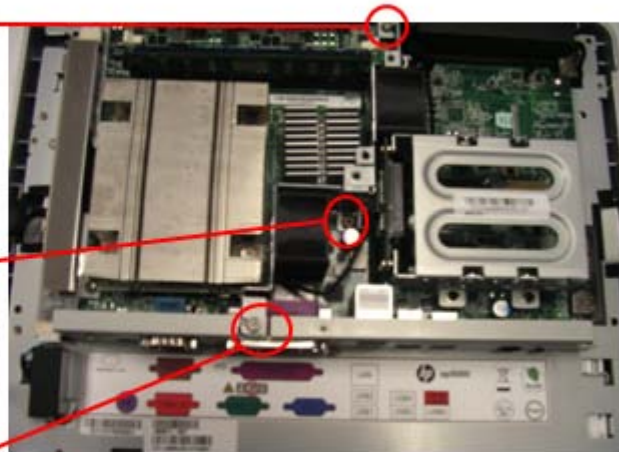
15

Take off Air Duct

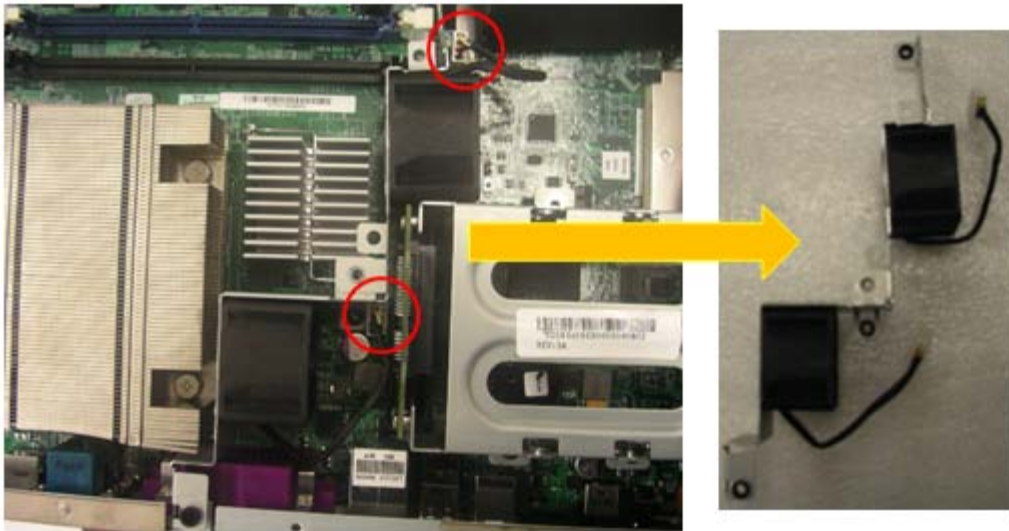


16

Release 3 pcs screw to take off Fan module from MB.

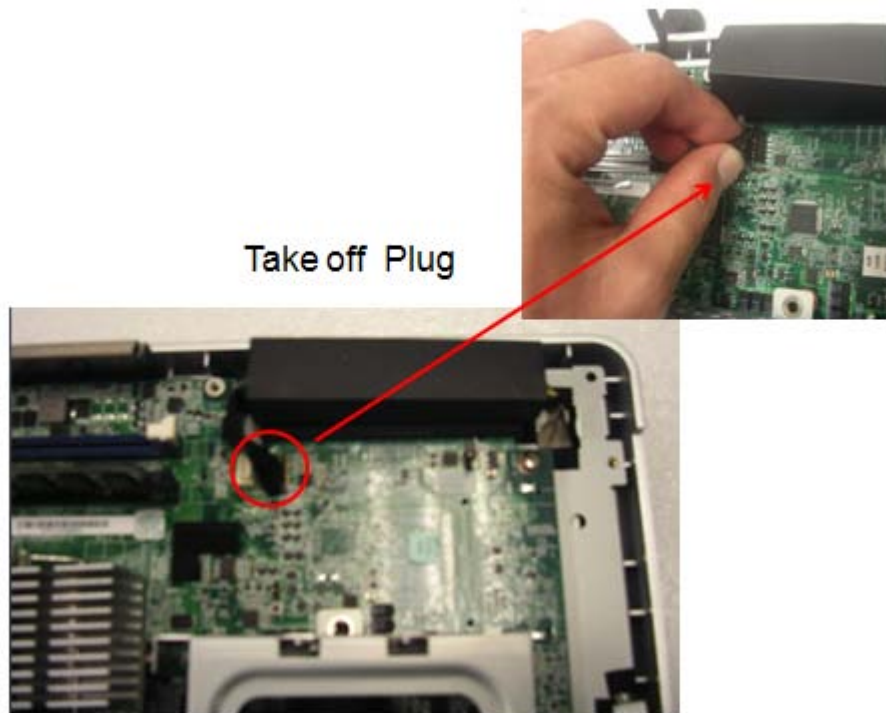


17 Take off Fan plugs and Remove Fan Module

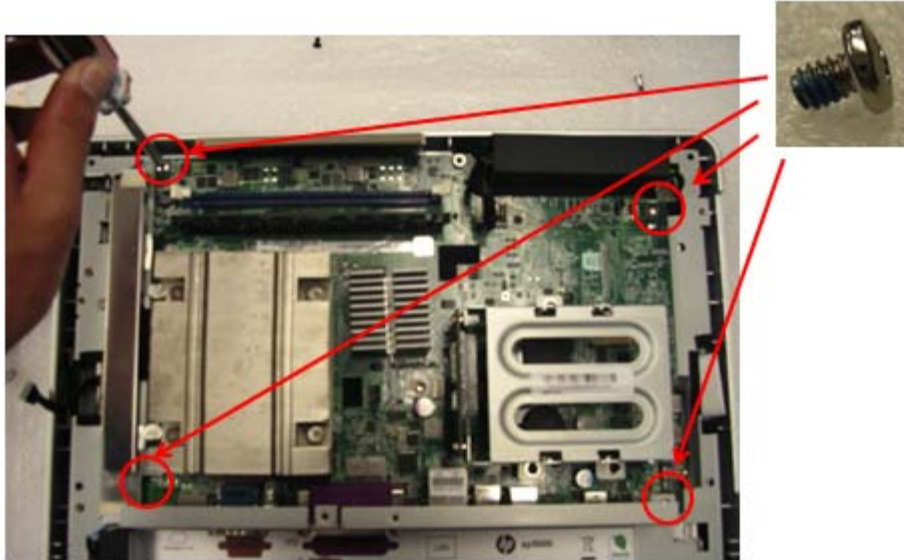


18

Take off Plug



19 Release 4 pcs screws to take off MB Module from LCD bracket



20 Pull the MB Module downward to take off it.



MB Module

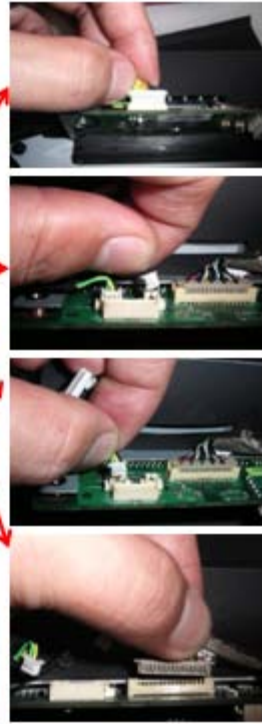


21

Take off all cables from PCI PCB.



Remove all Cables

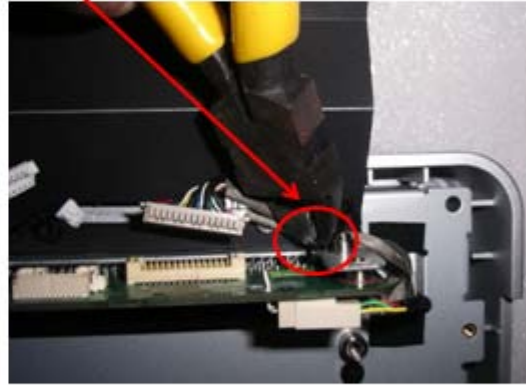
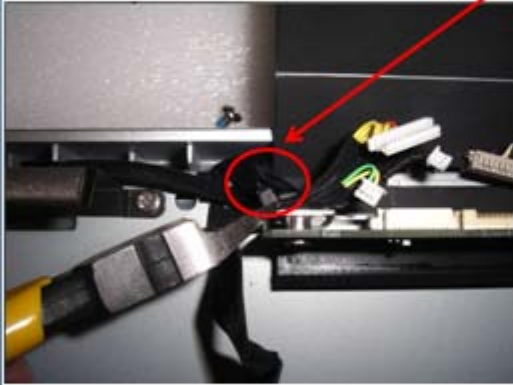


Open the Mylar covered on PCI.



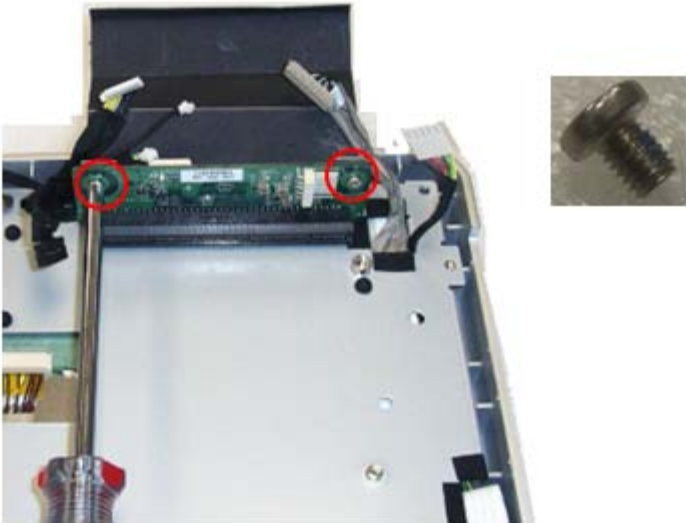
22

Cut out cable tie by Dikes Pliers.



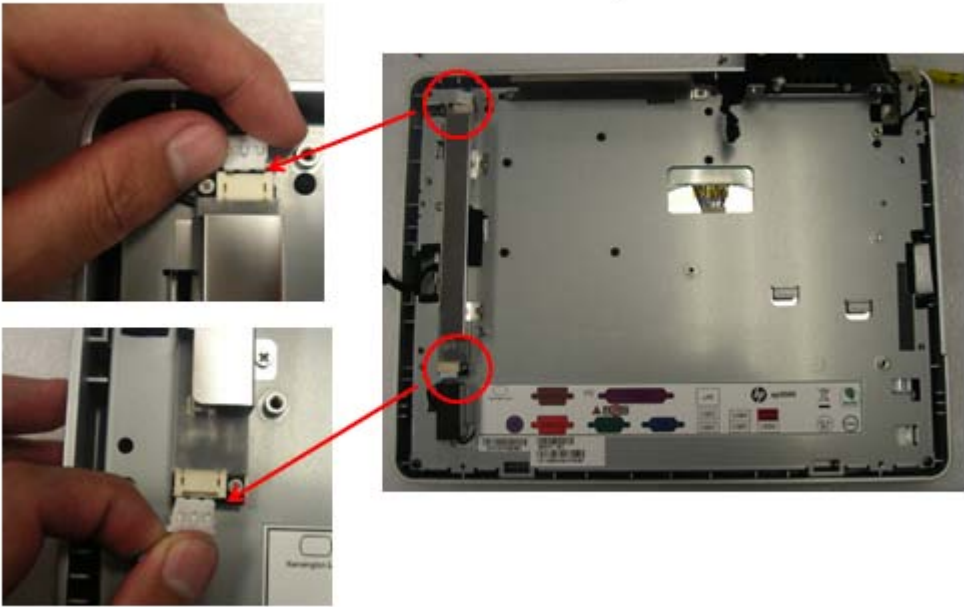
23

Release 2 pcs screws to Remove PCI PCB.

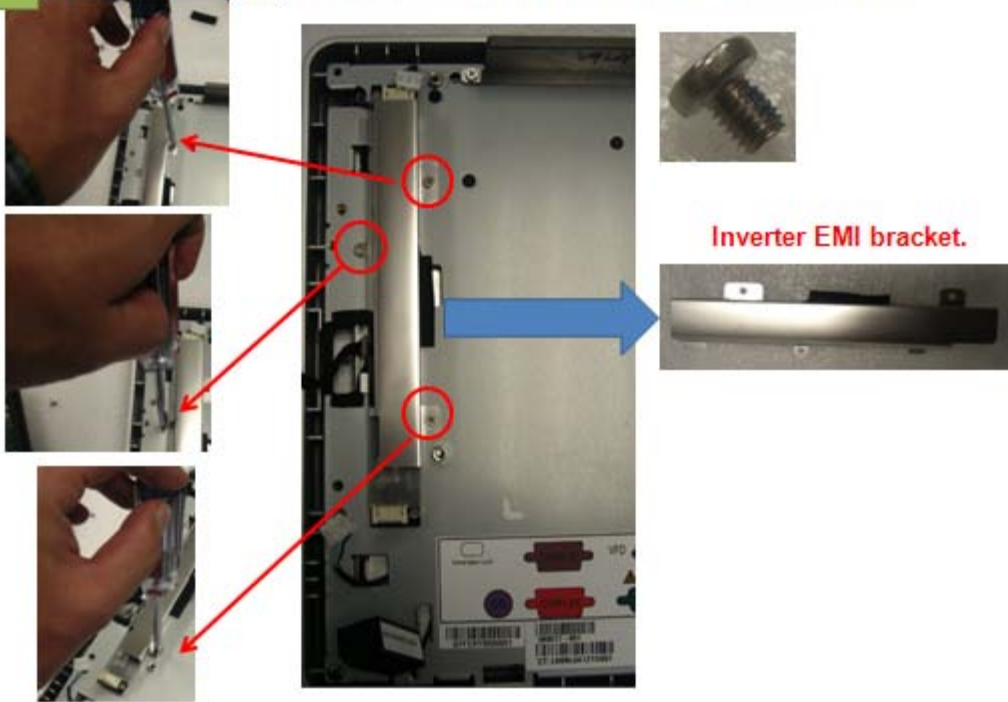


24

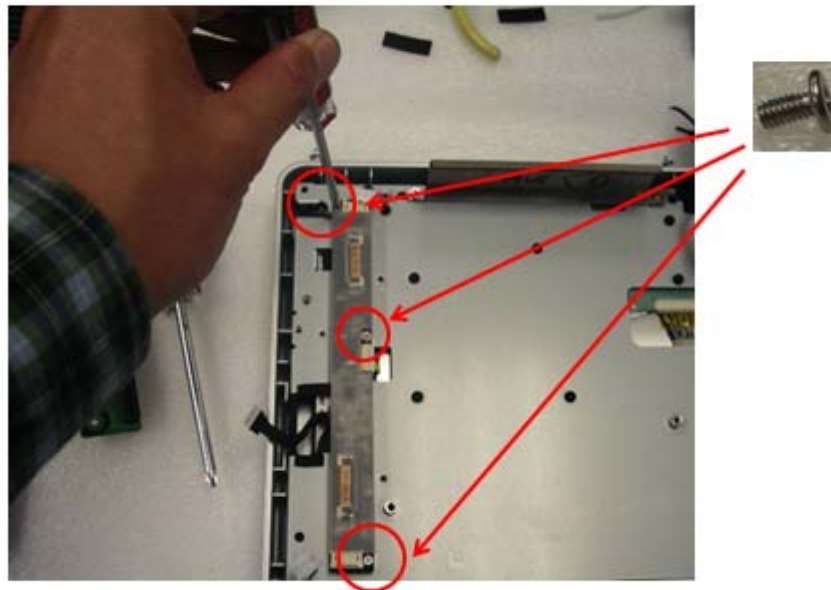
Take off two pcs of Cable.



25 Release 3 pcs screws to Remove Inverter EMI bracket.

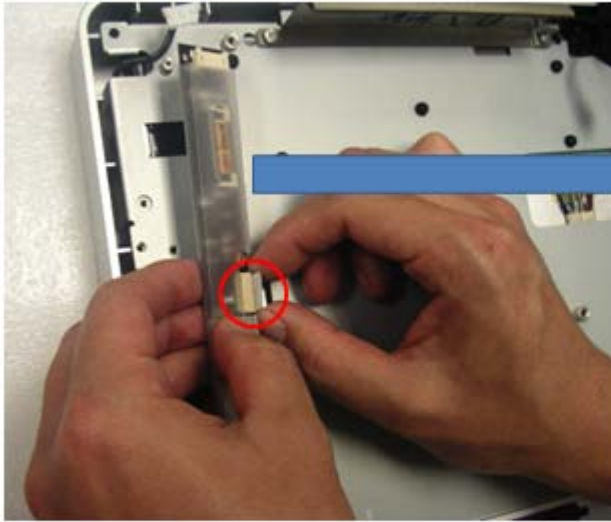


26 Release 3 pcs screws fixing Inverter PCB.



27

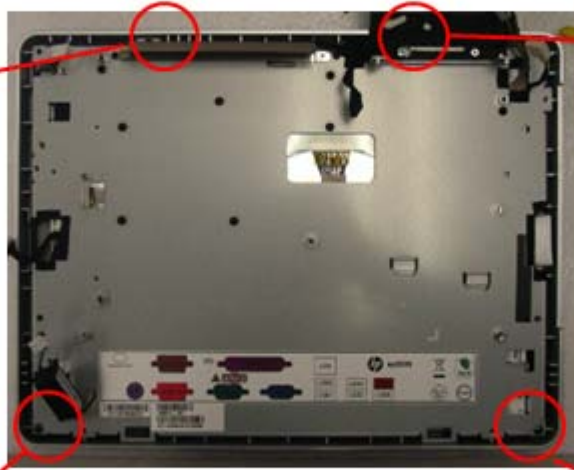
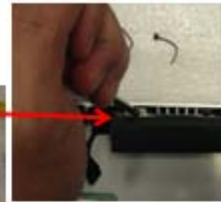
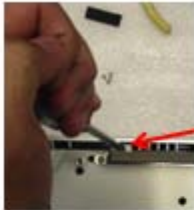
Take off cable to remove Inverter PCB.



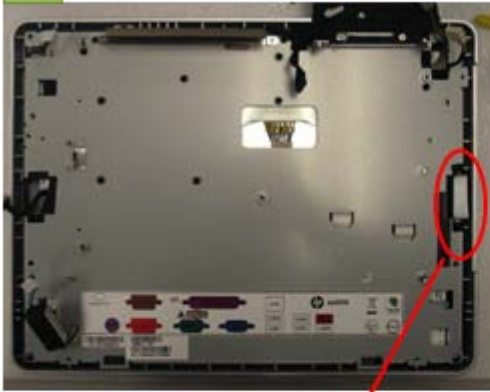
remove Inverter PCB

28

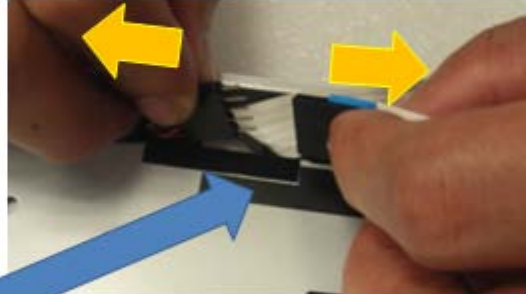
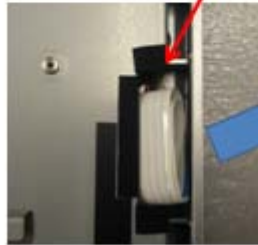
Release 4 pcs screws fixing LCD bracket with Front Cover.



29

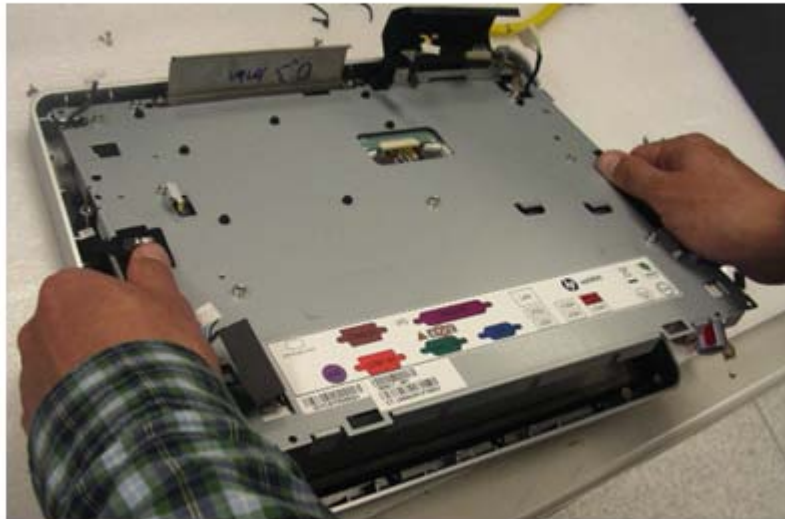


Take off connectivity of touch panel cable.



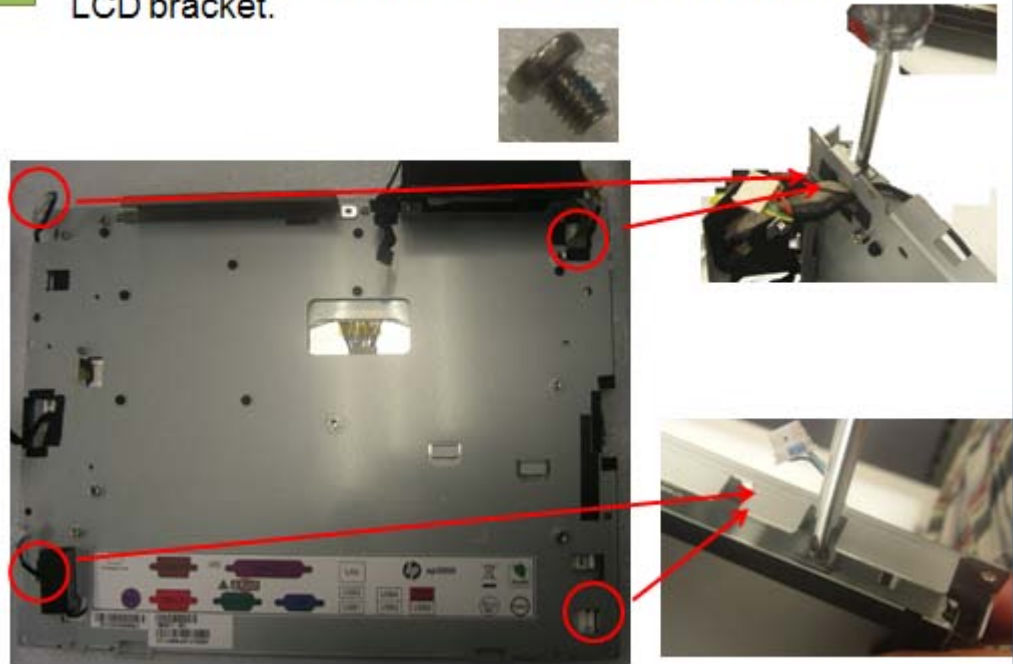
30

Take off LCD module from Front Cover Assembly.



31

Release 4 pcs screws to take off LCD panel from LCD bracket.



32

LCD panel



LCD bracket

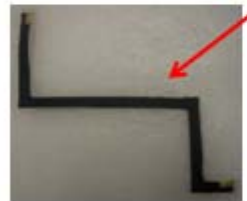


33

Take off all cables from LCD bracket.



Touch Panel cable



Inverter Cable



MSR cable



Speaker Cable



34

Disassemble Front Cover Assembly



LED cable



Front seal rubber



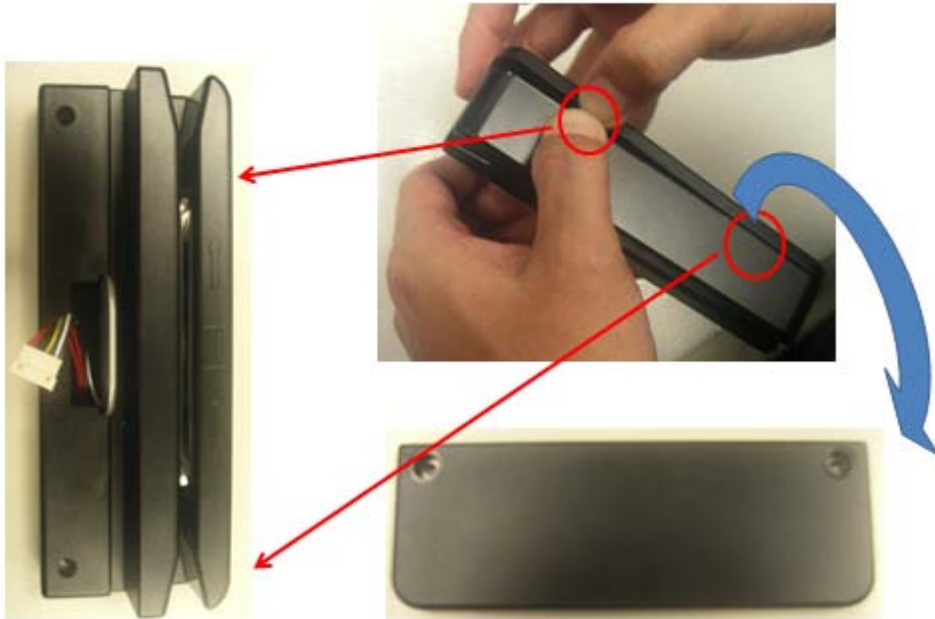
Touch panel



Front Cover

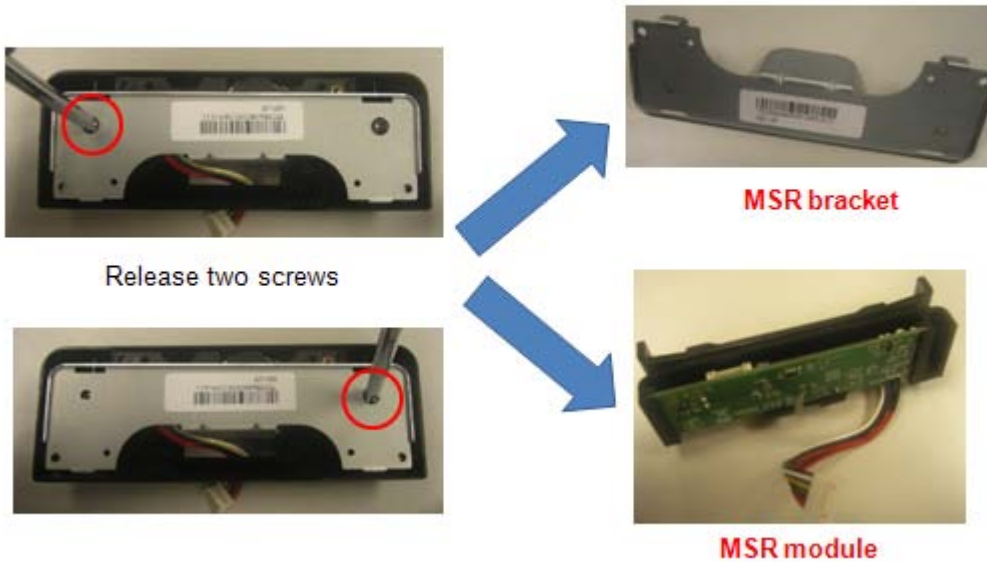
35

Click MSR side wall to take off MSR back cover.

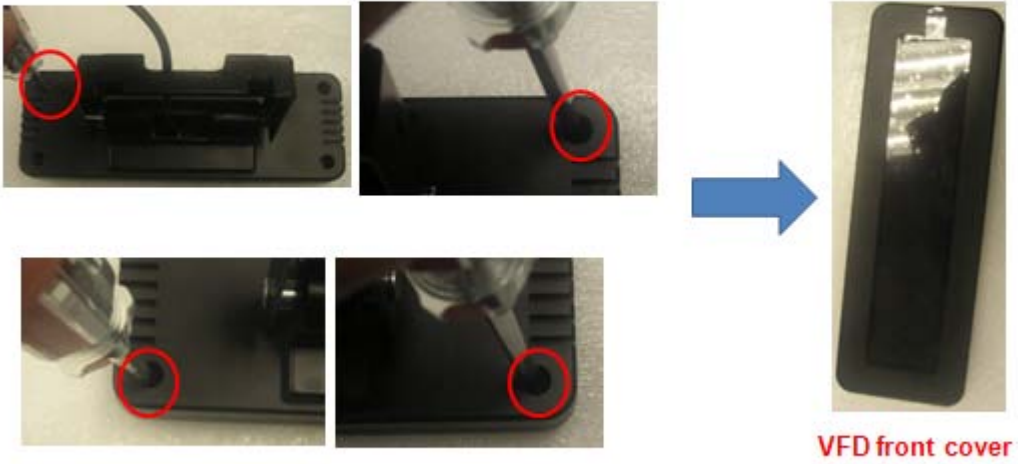


36

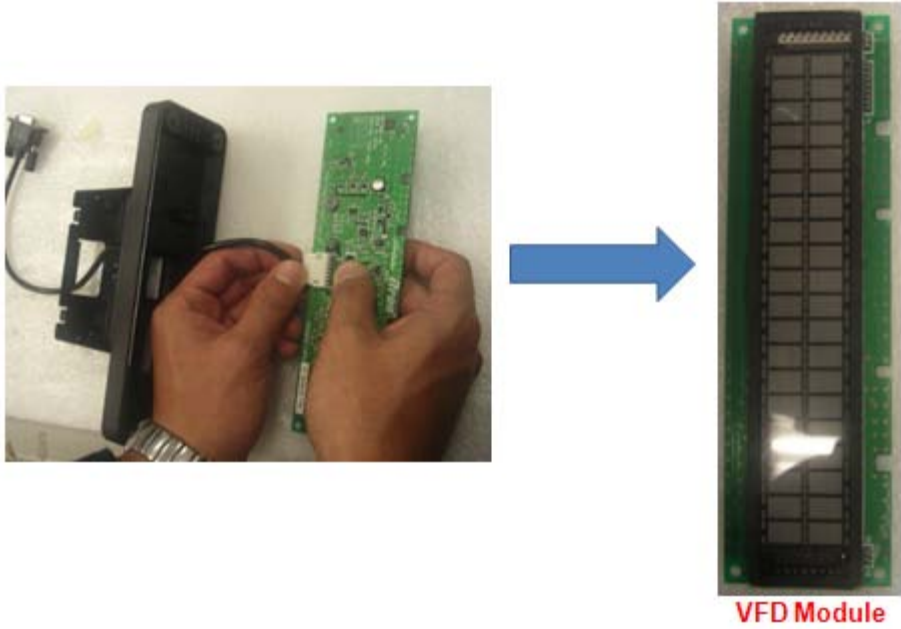
Release two screws to take off MSR module and bracket from MSR front cover.



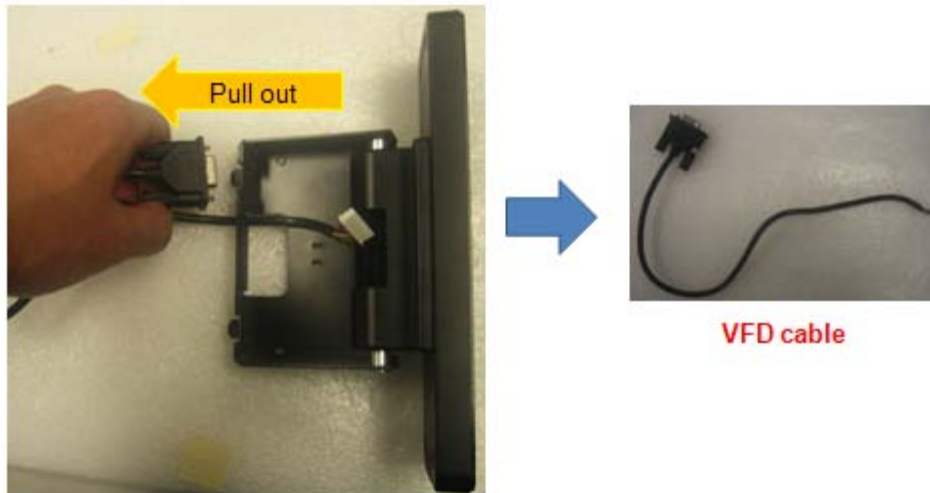
37 Release four screws to take off VFD front cover.



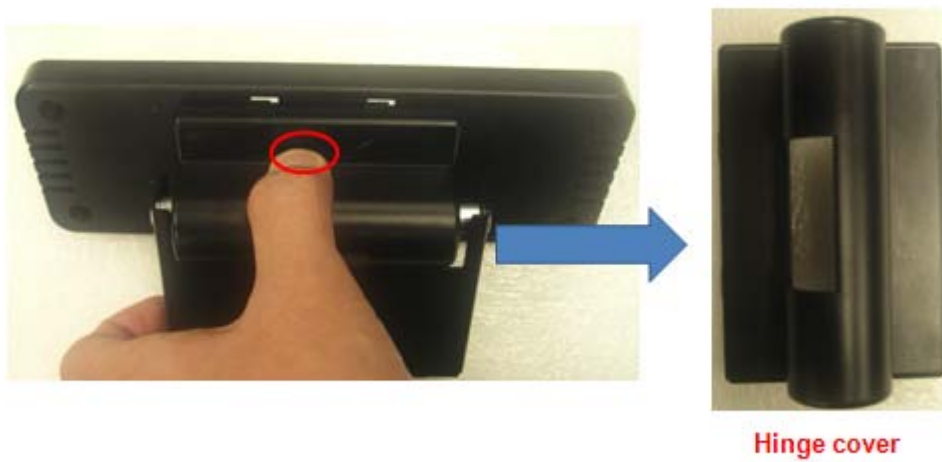
38 Un-connect VFD cable and take off VFD Module.



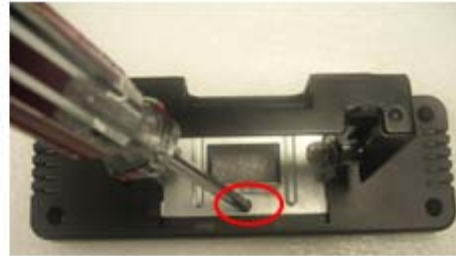
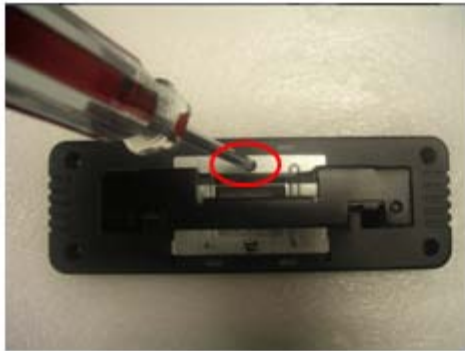
39 Pull out VFD cable through VFD back cover and Hinge.



40 Click red circle area to take off Hinge cover.



41 Release 2 pcs fixing Hinge bracket with MSR back cover.



42 Pull VFD hinge bracket downward to remove it.

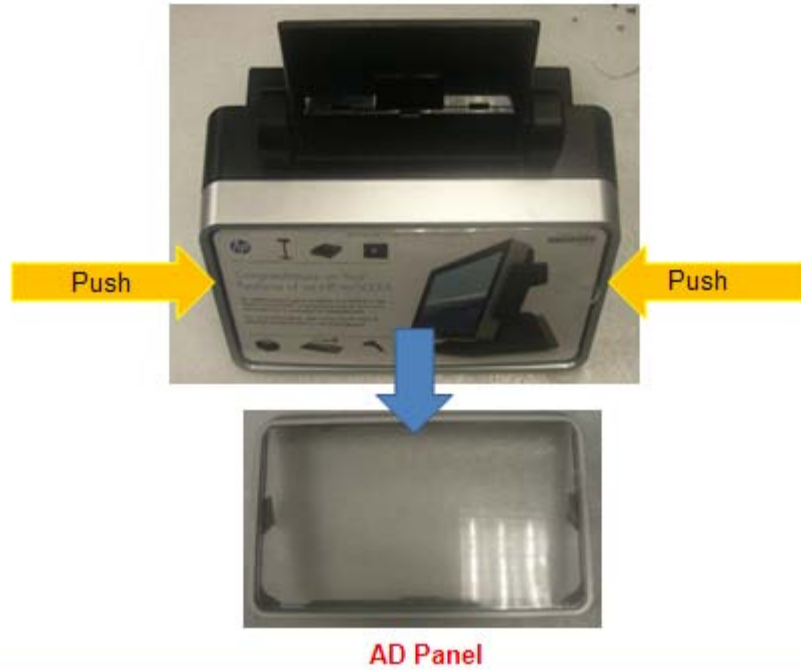


VFD Back Cover



VFD Hinge bracket

43 Pull silver AD panel both side to remove it.

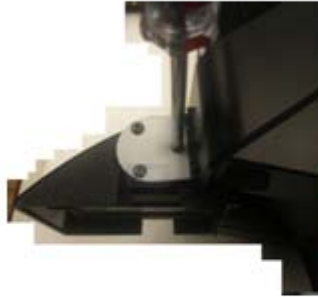


44 Take off base ear both side.



45

Release 3 pcs screws both side and Take off base cover and base hinge.



Release Screw



Base Hinge



Base cover

46

Release thumb screw fixing adapter bracket with Stand.



Release Thumb screw

47

Take off adapter bracket and adapter from base assembly.



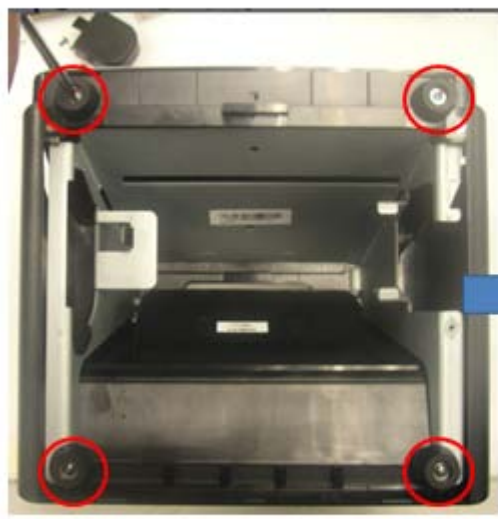
adapter bracket



Adapter

48

Release four screws to take off stand foot rubber

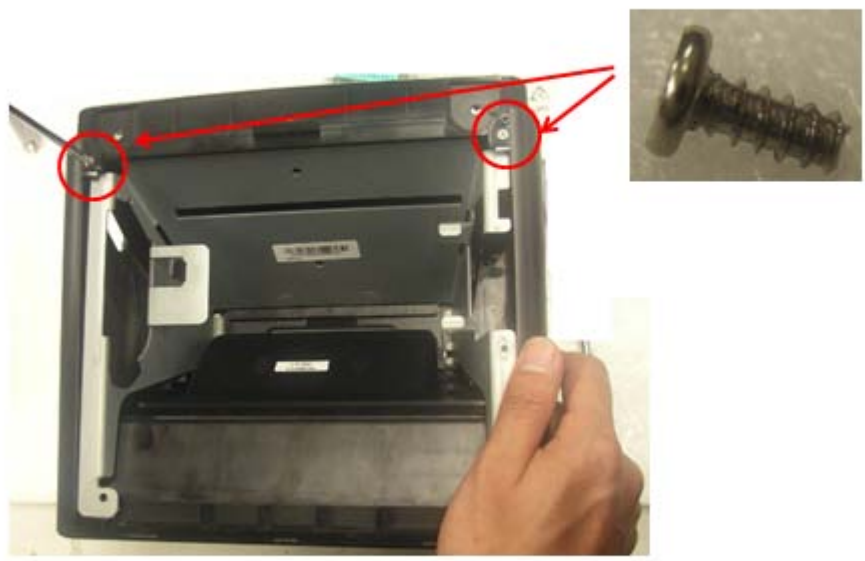


Release Screw

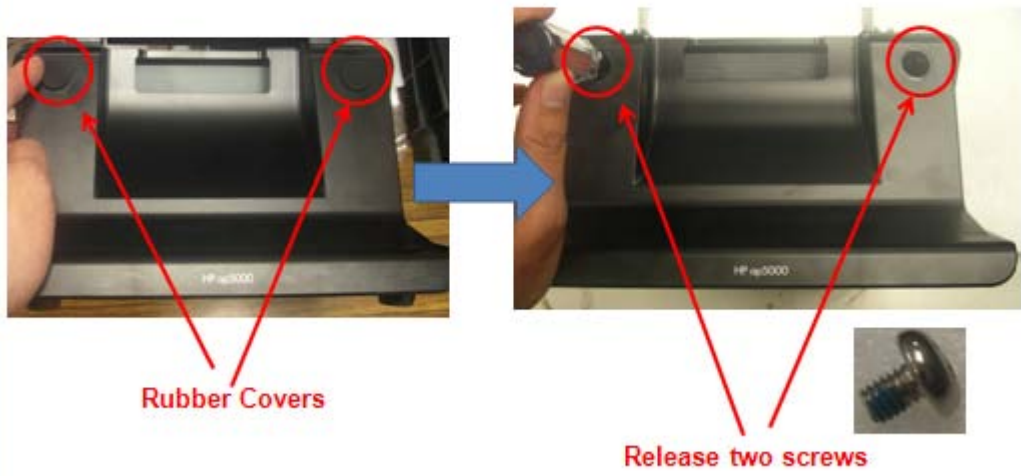


stand foot rubber

49 Release two screws at bottom side.



50 Take off two rubber covers and Release two screws.



51 Take apart Base assembly



Base Cap

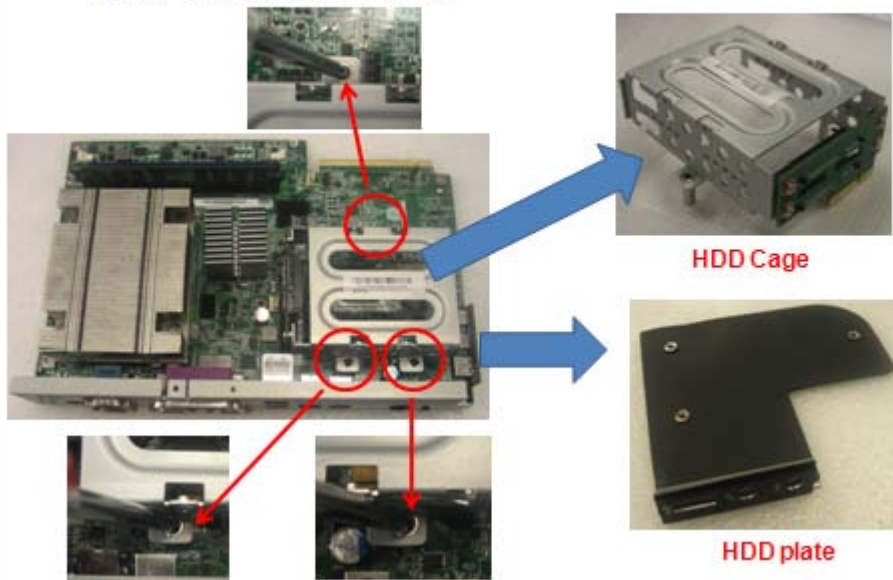


Stand Bracket



Base

52 Release 3 pcs screws to take off HDD Cage(with HDD back PCB) and HDD plate



HDD Cage

HDD plate

53

Take off HDD board and Cage bracket



Release 4 pcs screws



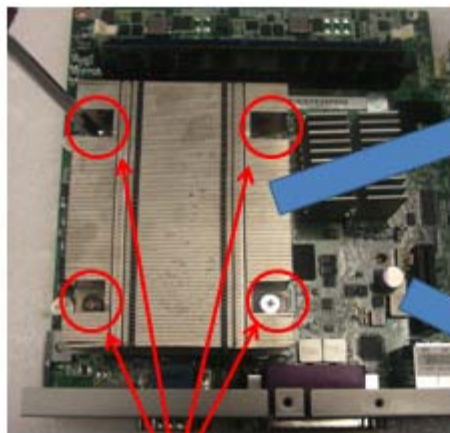
HDD board



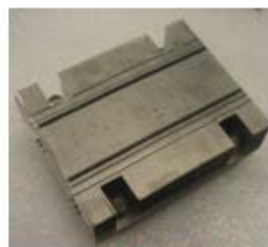
Cage bracket

54

Take off Heat Sink and back plate by releasing four screws.



Release 4 pcs screws



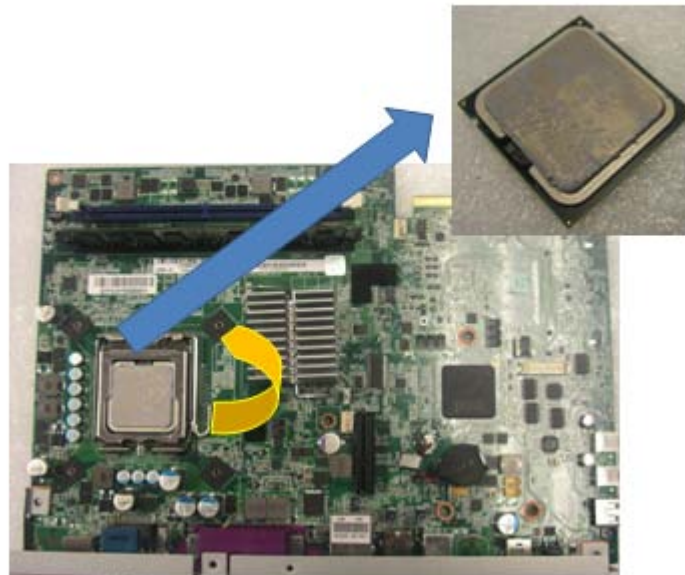
Heat Sink



Back Plate
At back side of MB .

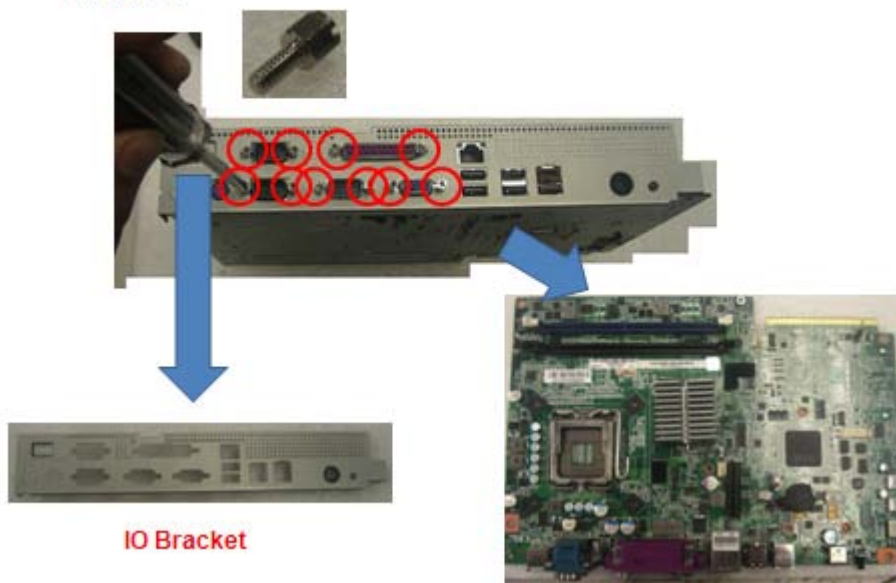
55

Take off CPU.



56

Release 10 pcs of Hexagon screw to take off IO Bracket and MB.



IO Bracket